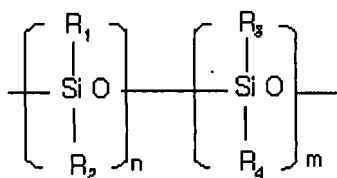


IN THE SPECIFICATION:

The specification as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~strikethrough~~.

Please REPLACE the paragraph beginning at page 4, line 3 and the paragraph beginning at page 5, line 5 (that is, paragraphs [0018] and [0019]), with the following paragraphs:

[0018] The second polymer layer 3 includes any material as long as it forms a dense layer and is stable during metal layer preparation, especially with respect to high temperatures and high pressure. Examples thereof are a ~~silicon-included~~ silicon-containing compound, polyalkylene oxide, polyolefin, polydiene, polyfluorocarbon, a mixture thereof, and a copolymer thereof. Generally, the ~~silicon-included~~ silicon-containing compound may be utilized. The ~~silicon-included~~ silicon-containing compound is represented by formula 1.



(1)

where R_1 , R_2 , R_3 , and R_4 are identically or independently selected from C_1 - C_{18} linear alkyls, or a branched alkyl, cyclic alkyl, alkenyl, aryl, aralkyl, halogenated alkyl, halogenated aryl, halogenated aralkyl, phenyl, mercaptan, methacrylate, acrylate, epoxy, or vinyl ether; and n and m are the same or different integers of 1 to 100,000.

[0019] The ~~silicon-included~~ silicon-containing compound is a thermosetting resin which does not melt and flow at high temperatures. In addition, during thermosetting, a Si-O-Si bond is generated in the ~~silicon-included~~ silicon-containing compound so that the compound is more impervious to heat. A higher thermosetting temperature decreases the thermosetting time, but the temperature is suitably controlled to temperature ranges in which modification of the polymer film does not occur.